



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

CHAD A. COBBLEY
TONGI JIANG
ED A. SCHROCK

Serial No. 08/916,629

Art Unit: 1733

Filing Date: AUGUST 22, 1997

Examiner: GALLAGHER, J.

For: SEMICONDUCTOR DIE ATTACHMENT
METHOD AND APPARATUS

Attorney Docket No. 97-0098

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V. day
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**PRELIMINARY AMENDMENT
SUBMITTED WITH CPA APPLICATION
UNDER 37 CFR 1.53(d)
September 22, 2000**

Assistant Commissioner for Patents
BOX CPA
Washington, D.C. 20231

Sir:

This Preliminary Amendment is submitted with a Continued Prosecution Application (CPA) being filed under 37 CFR 1.53(d).

This Preliminary Amendment is a response to the Final Office Action dated May 23, 2000 having a statutory period for response set to expire on August 23, 2000, but extended for 30 days by the enclosed Petition For Extension Of Time, until September 25, 2000.

Please amend the captioned case as follows.

In the claims:

1. (thrice amended) A method for packaging a semiconductor die to form a semiconductor package comprising:

C/subDI

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